

**PATENT ASSIGNMENT**

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SUBMISSION TYPE:	NEW ASSIGNMENT																
NATURE OF CONVEYANCE:	ASSIGNMENT																
<b>CONVEYING PARTY DATA</b>																	
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Hsiu-Ping WEI</td> <td>03/26/2010</td> </tr> <tr> <td>Shin-Puu JENG</td> <td>03/30/2010</td> </tr> <tr> <td>Hao-Yi TSAI</td> <td>03/26/2010</td> </tr> <tr> <td>Hsien-Wei CHEN</td> <td>03/26/2010</td> </tr> <tr> <td>Yu-Wen LIU</td> <td>03/26/2010</td> </tr> <tr> <td>Ying-Ju CHEN</td> <td>03/26/2010</td> </tr> <tr> <td>Tzuan-Horng LIU</td> <td>03/26/2010</td> </tr> </tbody> </table>		Name	Execution Date	Hsiu-Ping WEI	03/26/2010	Shin-Puu JENG	03/30/2010	Hao-Yi TSAI	03/26/2010	Hsien-Wei CHEN	03/26/2010	Yu-Wen LIU	03/26/2010	Ying-Ju CHEN	03/26/2010	Tzuan-Horng LIU	03/26/2010
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<b>RECEIVING PARTY DATA</b>																	
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.																
Street Address:	No. 8, Li-Hsin Rd. VI, Hsinchu Science Park																
City:	Hsinchu																
State/Country:	TAIWAN																
Postal Code:	300																
<b>PROPERTY NUMBERS Total: 1</b>																	
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>12757440</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	12757440												
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<b>CORRESPONDENCE DATA</b>																	
Fax Number:	(703)518-5499																
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>																	
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OP \$40.00 12757440

**501143897**

**PATENT  
 REEL: 024211 FRAME: 0446**

NAME OF SUBMITTER:

Randy A. Noranbrock

Total Attachments: 2

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### ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

- 1) Hsiu-Ping WEI
- 2) Shin-Puu JENG
- 3) Hao-Yi TSAI
- 4) Hsien-Wei CHEN
- 5) Yu-Wen LIU
- 6) Ying-Ju CHEN
- 7) Tzuan-Horng LIU

who has made a certain new and useful invention, hereby sells, assigns and transfers unto

**TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.** having a place of business at **No. 8, Li-Hsin Rd. VI, Hsinchu Science Park, Hsinchu 300, Taiwan R.O.C.**

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

**PACKAGE STRUCTURE AND METHOD FOR REDUCING DIELECTRIC LAYER DELAMINATION**

- (a) for which an application for United States Letters Patent was filed on 4-9-10, and identified by United States Patent Application No. 12/757,440; or
- (b) for which an application for United States Letters Patent was executed on \_\_\_\_\_,

and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefore and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside my signature:

1) Hsiu-Ping Wei  
Name: Hsiu-Ping WEI

2010.03.26  
Date:

2) [Signature]  
Name: Shin-Puu JENG

2010.3.30  
Date:

3) Hao-Yi Tsai  
Name: Hao-Yi TSAI

2010.03.26  
Date:

4) Hsien-Wei Chen  
Name: Hsien-Wei CHEN

2010.03.26  
Date:

5) Yu-Wen Liu  
Name: Yu-Wen LIU

2010.03.26  
Date:

6) Ying-Ju Chen  
Name: Ying-Ju CHEN

2010.03.26  
Date:

7) Tzuan-Hong Liu  
Name: Tzuan-Hong LIU

2010.03.26  
Date: